

News Release

12th January 2018

In December 2017, SEMICAPS responded to Hamamatsu's Inter Partes Review filings (IPR2017-02110 and IPR2017-02112) against claims of our US Patent 7,623,982 B2. SEMICAPS has filed a lawsuit in the Northern District of California alleging infringement of claims of this patent in June 2017.

SEMICAPS's case is supported by Dr Michael (Mike) Bruce the foremost expert in the area of static and dynamic laser based localization techniques used in the failure and yield analysis of semiconductors. Mike holds 79 patents. Among these, his Soft Defect Localization technique is acknowledged by a 2015 review in the EDFA magazine as "*perhaps the greatest innovation*" in this area.

In his supporting declaration Dr Bruce noted that the IPR depended heavily upon 2 cited references: Hamada (Japanese Patent Publication 2003-179108) and Quah (DC-Coupled Laser Induced Detection System for Fault Localization in Microelectronic Failure Analysis, Proceedings of the 13th IPFA, Singapore 2006, pp. 327-332). However, Mike asserts that neither of these discloses a pulsed laser. Further, he also noted that Hamada does not disclose the key aspect of taking a plurality of samples from a signal response. This aspect is the main limitation in claim 1 of the '982 patent. In addition, Dr Bruce pointed out that Hamada's test signal is dynamic in nature, unlike the static test signal used in the '982 patent. This clearly shows that the 2 systems are fundamentally different in nature.

SEMICAPS continues to believe that it has a strong position in this patent dispute. Documents related to this IPR are publicly available and can be found on the USPTO website. Please go to <https://ptab.uspto.gov/> and search for SEMICAPS in the %Party Name+box.

About SEMICAPS

SEMICAPS is the world's most technologically advanced company in the field of failure localization analysis in semiconductors. Used by leading companies like GlobalFoundries, AMD and Intel for their design-debug and yield analyses, the SEMICAPS laser probe microscope is capable for semiconductor technology nodes as small as 10 nm. Further, besides the standard laboratory configurations, the SEMICAPS Wafer Probing platform, the SEMICAPS 5000, allows semiconductor wafer of complex logic chips to be analysed without the need for sorting, dicing and packaging. This saves weeks for foundries undergoing their yield enhancement cycle.

SEMICAPS, founded in 1988, is a technology spinoff from the National University of Singapore.